

# Single-Photon Time-of-Flight Sensors for Spacecraft Navigation and Landing in CMOS Technologies

---

David Stoppa

*Fondazione Bruno Kessler, Trento, Italy*



FONDAZIONE  
BRUNO KESSLER

Section V.C: Electronic Nanodevices and Technology Trends

**NanoInnovation 2016**

Rome 20-23 September 2016

# Outline

---

- Operation Principle of Geiger-mode APD (SPAD)
- Implementation of CMOS SPADs
- Single-Photon Detectors at FBK: CMOS and Full Custom technologies
- 3D ranging/imaging for space applications
- SPAD-based TOF Sensor Architecture
- Experimental results
- Conclusions

# Acknowledgments

---

- All my colleagues: IRIS-FBK Team
- Special thanks to: Matteo Perenzoni
- CSEM team (V. Mitev, J. Haesler, C. Pache, T. Herr, A. Pollini)
- European Space Agency
- *Sensor details presented at ISSCC'16 , 1-4 Feb., San Francisco, USA*

# Photodiode, APD, SPAD

- SPAD = photodiode biased beyond its breakdown voltage (Geiger mode)

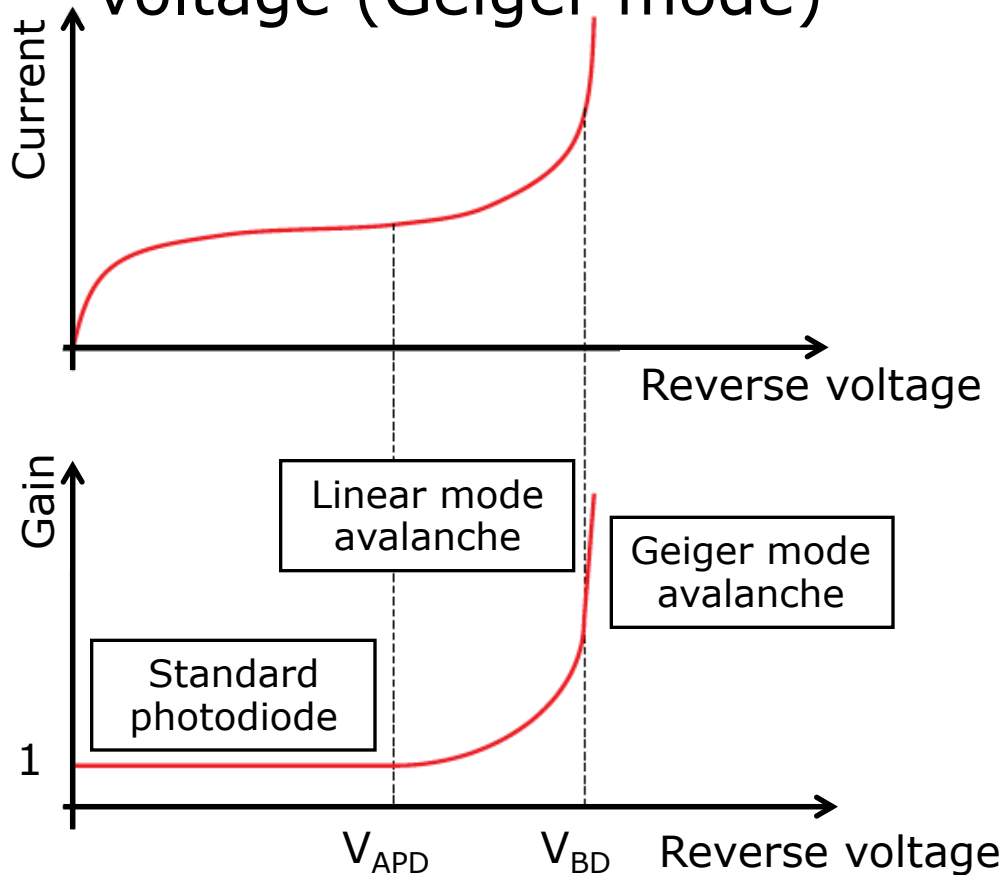
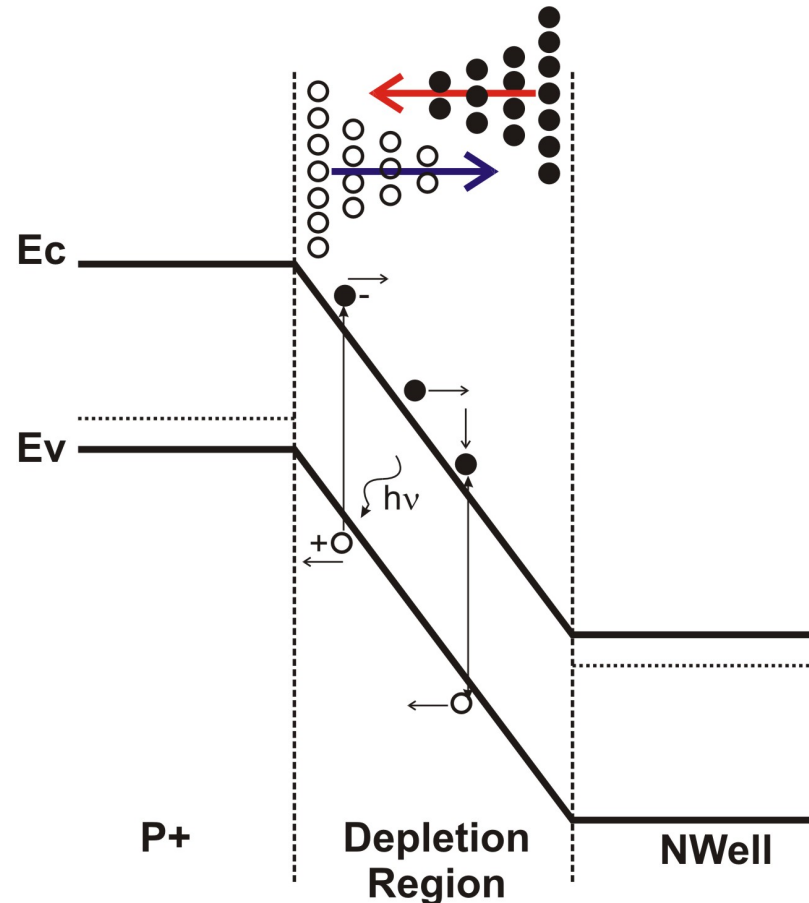


Photo-multiplication effect allows for **SINGLE PHOTON DETECTION**

# Avalanche and Breakdown

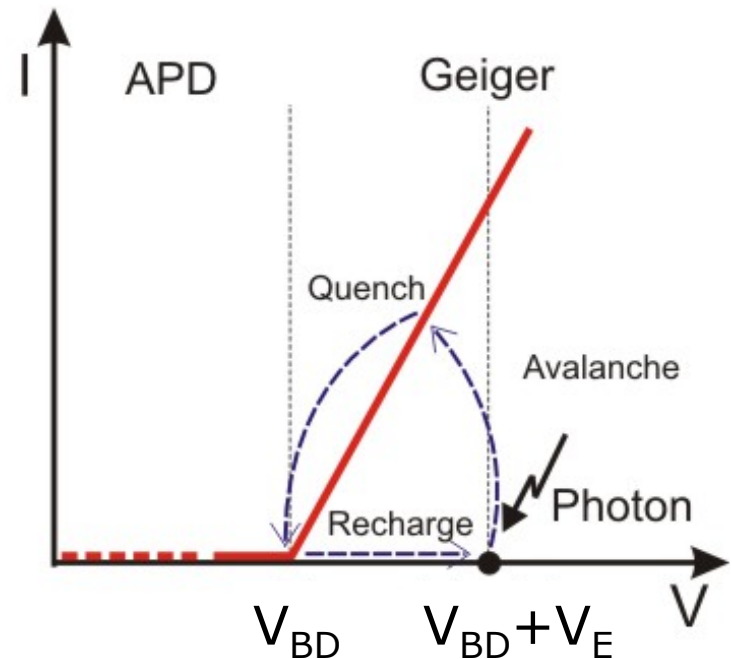
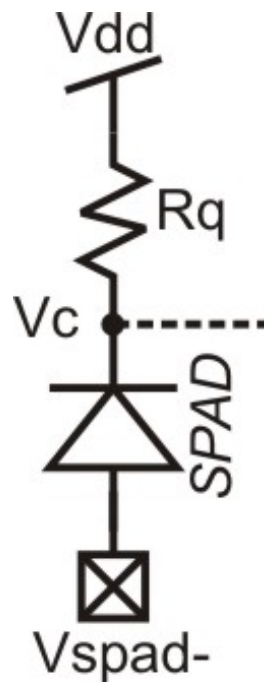
- High electric field within depletion region needed to reach breakdown



# SPAD Operation

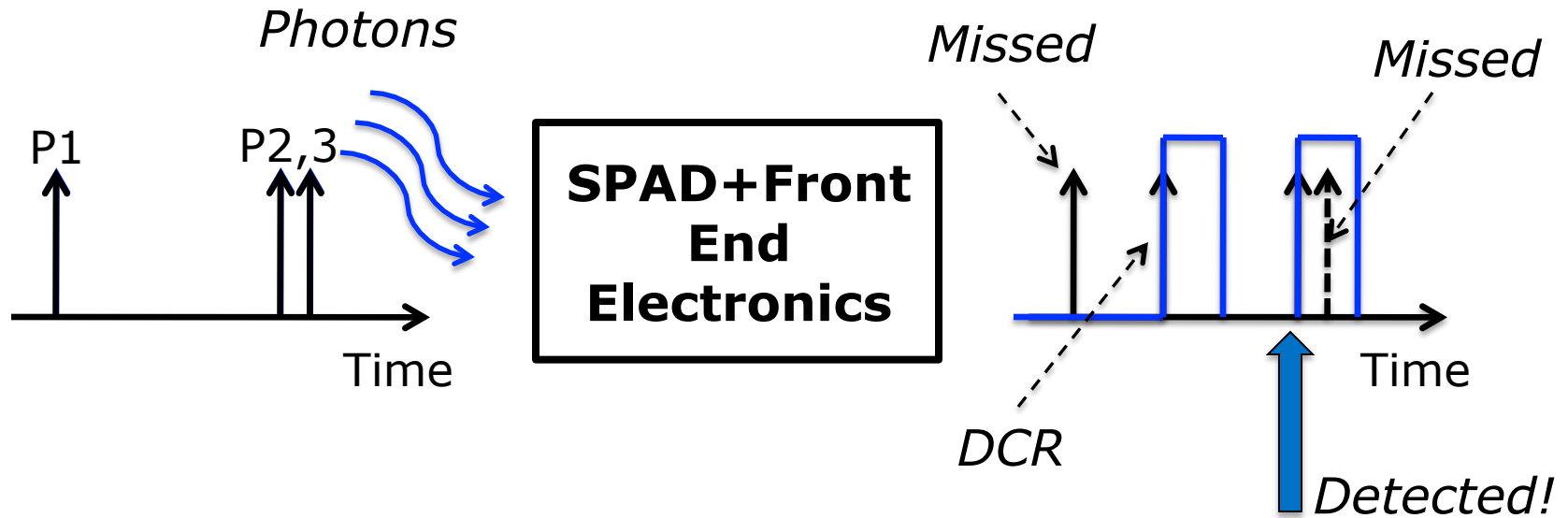
## □ Operation Loop:

- 1. Entering the Geiger region at  $V_{BD} + V_E$  (meta-stable point)
- 2. Avalanche
- 3. Quenching
- 4. Recharging to 1



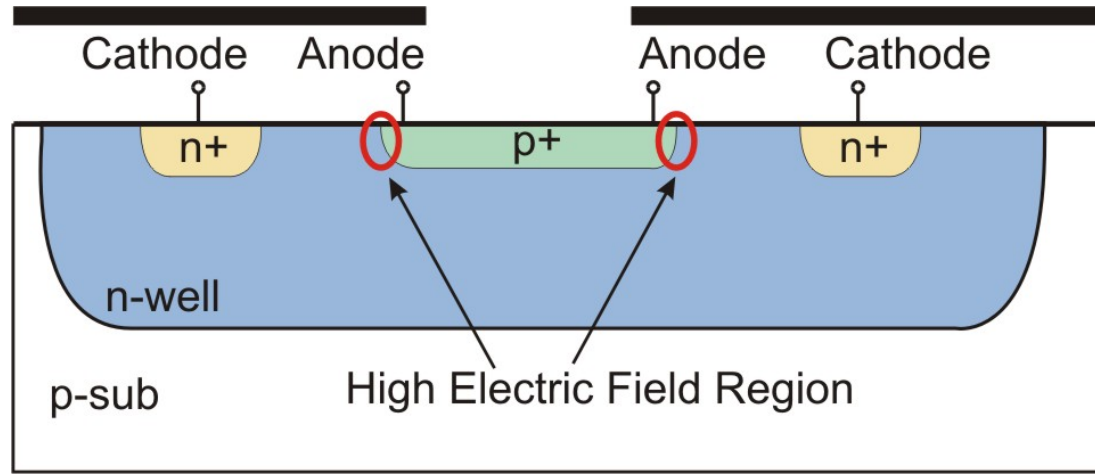
$V_E$ : Excess bias voltage

# SPAD High Level Behavior

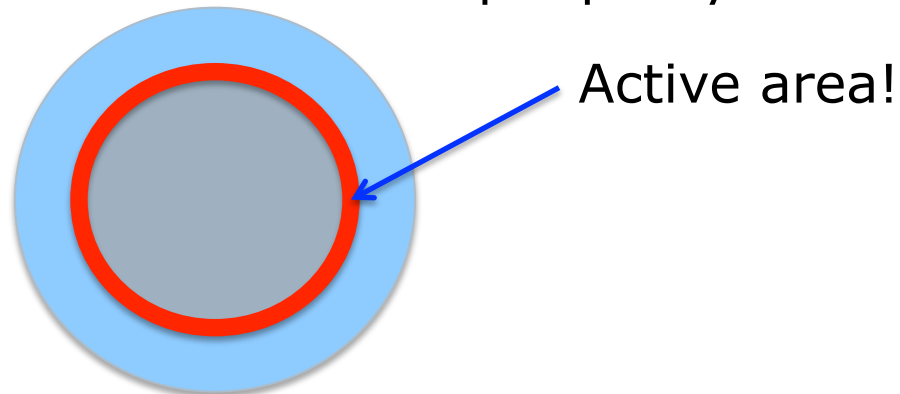


- ❑ Detected photons generate digital pulses
- ❑ Not all the photons are detected!
- ❑ Pulses are generated also in dark condition (DCR noise)
- ❑ Jitter noise between detected photon and digital output

# SPAD with a simple $pn$ Junction?



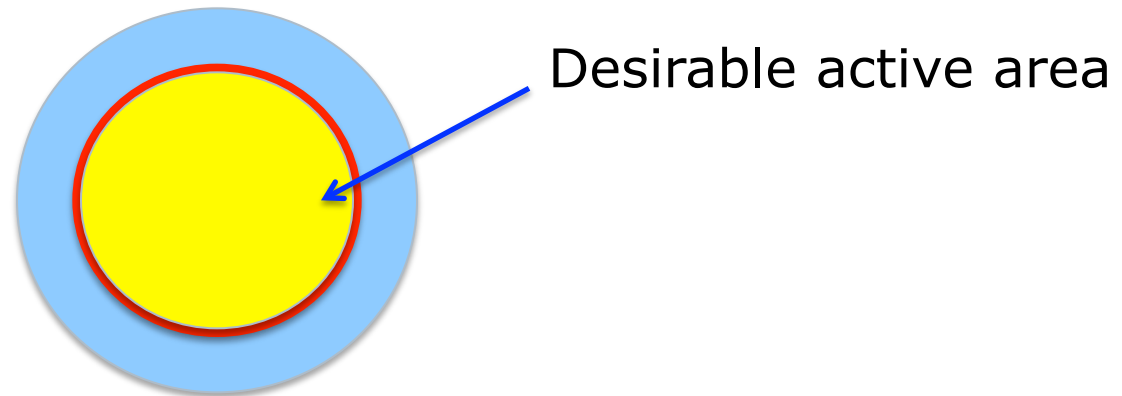
- At the edges (shallow junctions) high electric fields
- Premature breakdown at the sensor periphery





# SPAD with a simple $pn$ Junction?

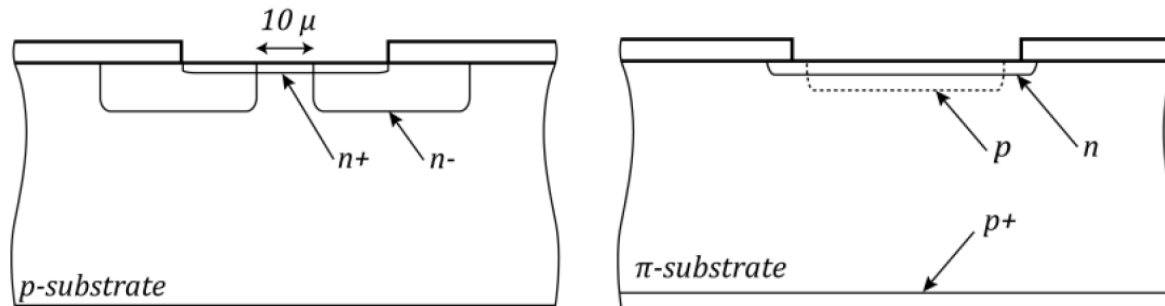
---



- Guard-ring structure is needed to prevent breakdown at the periphery while keeping the avalanche region confined in the planar area

# SPADs out of the Labs (Eventually!)

- SPAD known since 60's (!)

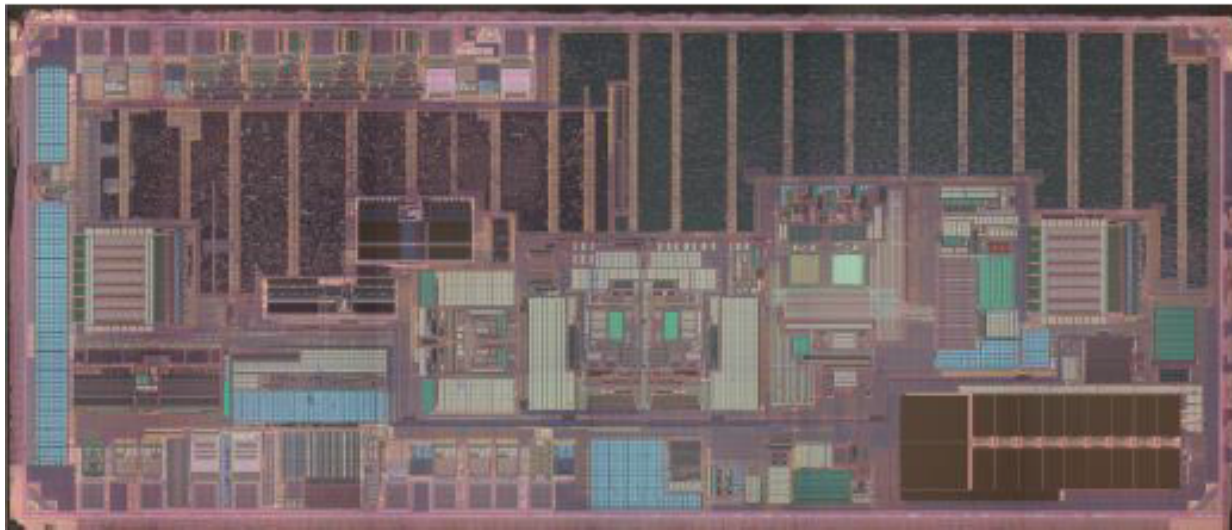


- [1] R. J. McIntyre, *Theory of Microplasma Instability in Silicon*, J. of Applied Physics, pp. 983-995, 1961.  
[2] R. H. Haitz, *Model for the Electrical Behavior of a Microplasma*, J. of Applied Physics, pp. 1370-1376, 1964.

- First CMOS implementations about fifteen years ago
- CMOS SPADs entered the market in 2012-2013

# From high-end applications to consumer

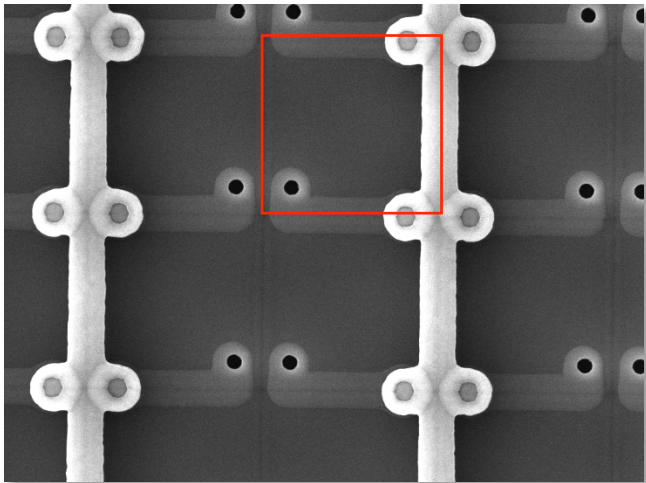
## □ STM SPAD-based TOF Proximity Sensor



@Chipworks (<http://ww2.chipworks.com/e/4202/6180-Time-of-Flight-Sensor-pdf/hwvfs/713665047>)

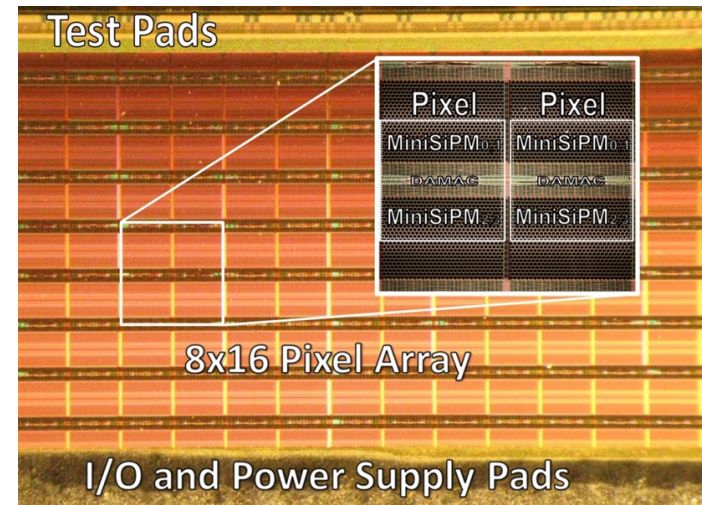
# Single-Photon Detectors at FBK

## Single-Photon Avalanche Diodes



### Custom technology (FBK process):

- high efficiency
- low noise
- high flexibility

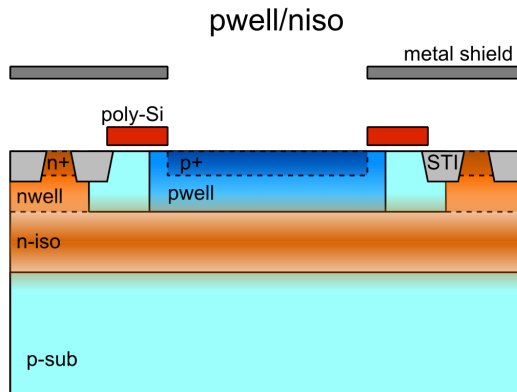


### Standard CMOS technology:

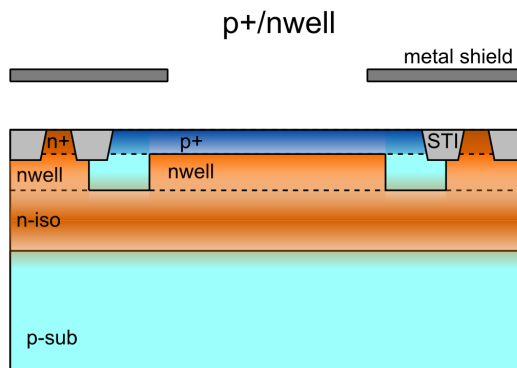
- smart architecture
- high-level integration

# FBK CMOS SPAD in LFoundry 150nm

- First testchip (Langshut), 2010/2011: two SPADs, published at ESSDERC 2011



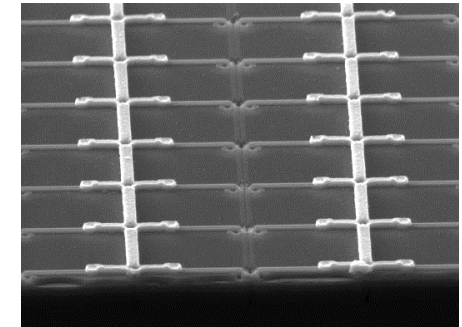
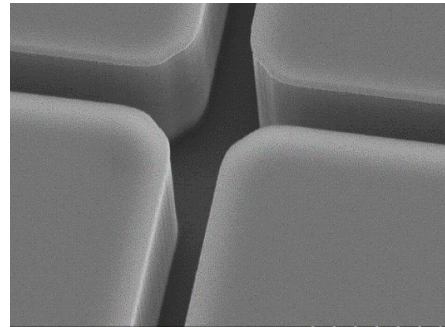
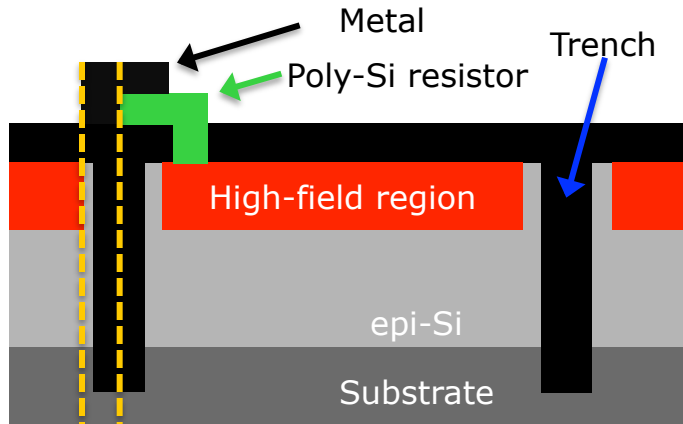
- Deep junction  $> 0.5\mu\text{m}$
- Virtual guard ring
- Graded doping profiles



- Shallow junction  $\sim 0.2\mu\text{m}$
- p-sub low-doped guard ring
- Steep p+ doping profile

# Full Custom Technology: FBK SiPM

- Specialized process offers superior performance:  $DCR < 200 \text{ kHz/mm}^2$



Dead border <  $2 \mu\text{m}$

## Different cells...

Cell pitch	Fill factor
15 $\mu\text{m}$	62 %
20 $\mu\text{m}$	66 %
25 $\mu\text{m}$	73 %
30 $\mu\text{m}$	77 %
35 $\mu\text{m}$	81 %
40 $\mu\text{m}$	83 %

## Different SiPM layouts

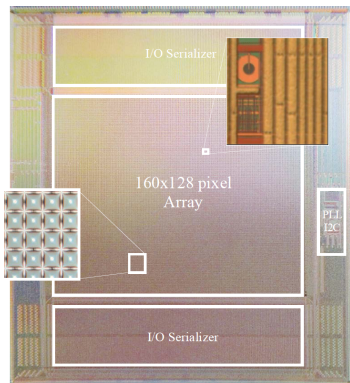
Active area	Cell pitch
1x1 $\text{mm}^2$	15 / 20 / 25 / 30 $\mu\text{m}$
Coming soon	
1x1 $\text{mm}^2$	35 / 40 $\mu\text{m}$
4x4 $\text{mm}^2$	30 / 35 / 40 $\mu\text{m}$
6x6 $\text{mm}^2$	30 $\mu\text{m}$

[28] A. Ferri et Al., NSS'15

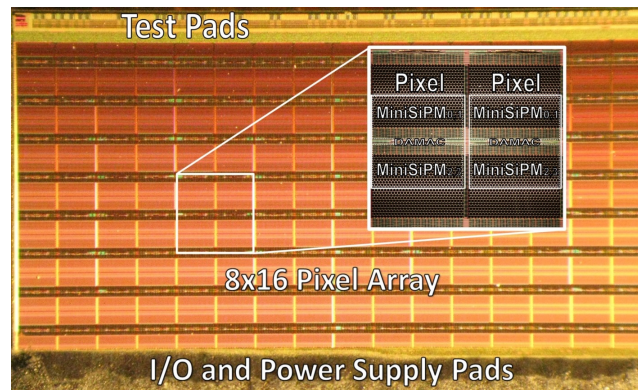
# CMOS SPAD Sensors at FBK

- Developments originally driven by Biomedical applications
- Several different 'families' of sensors developed
- Three examples shown here:

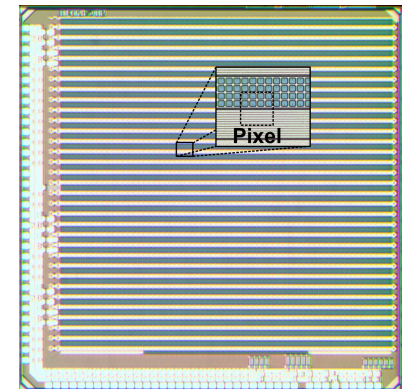
*Lifetime Imaging*



*Positron Emission Tomography*



*3D Imaging*



**MEGAFRAME FP7-Project**

[www.megaframe.eu](http://www.megaframe.eu)

**Single SPAD + TDC**

[Veerappan, ISSCC 2011]

**SPADnet FP7-Project**

[www.spadnet.eu](http://www.spadnet.eu)

**D-SiPM + TDCs**

[Braga, ISSCC 2013]

**MILA ESA-Project**

[iris.fbk.eu/projects/mila](http://iris.fbk.eu/projects/mila)

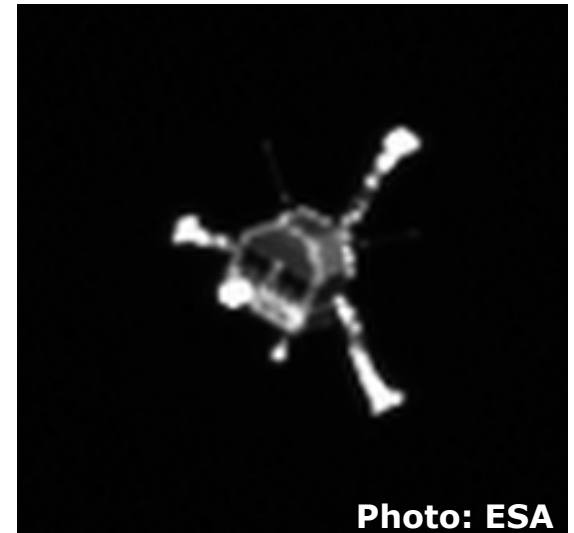
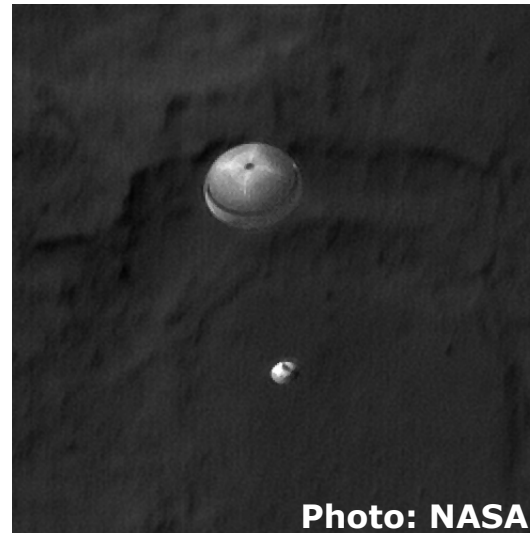
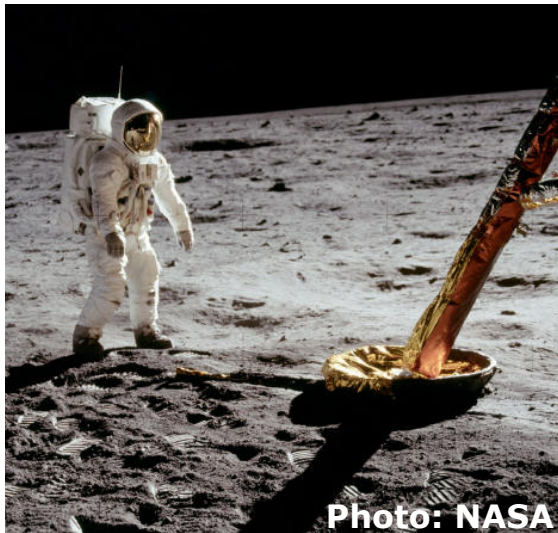
**D-SiPM + TDC**

[Perenzoni, ISSCC 2016]

# Landing in Space

---

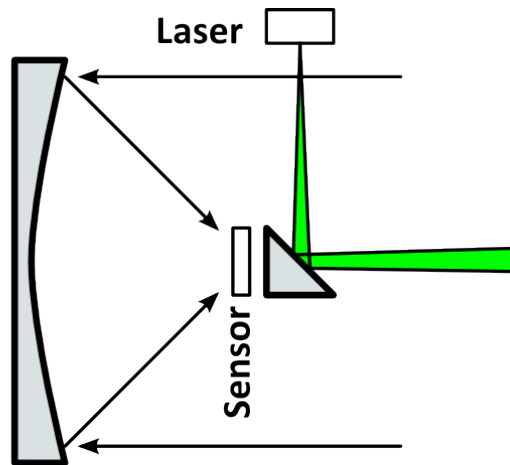
- Apollo 11 mission on the Moon
- Mars Space Laboratory on Mars
- Rosetta mission on comet 67P/C-G



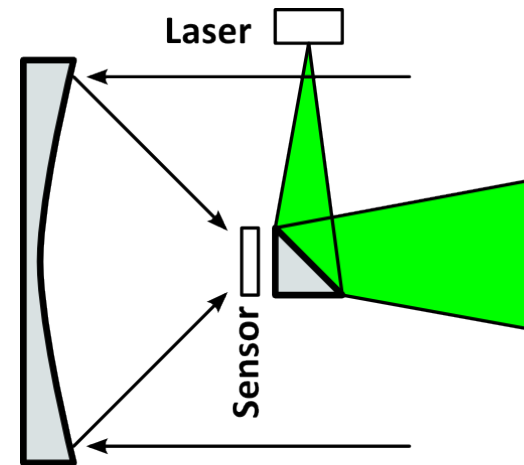


# Long Measurement Range

## *Altimeter*



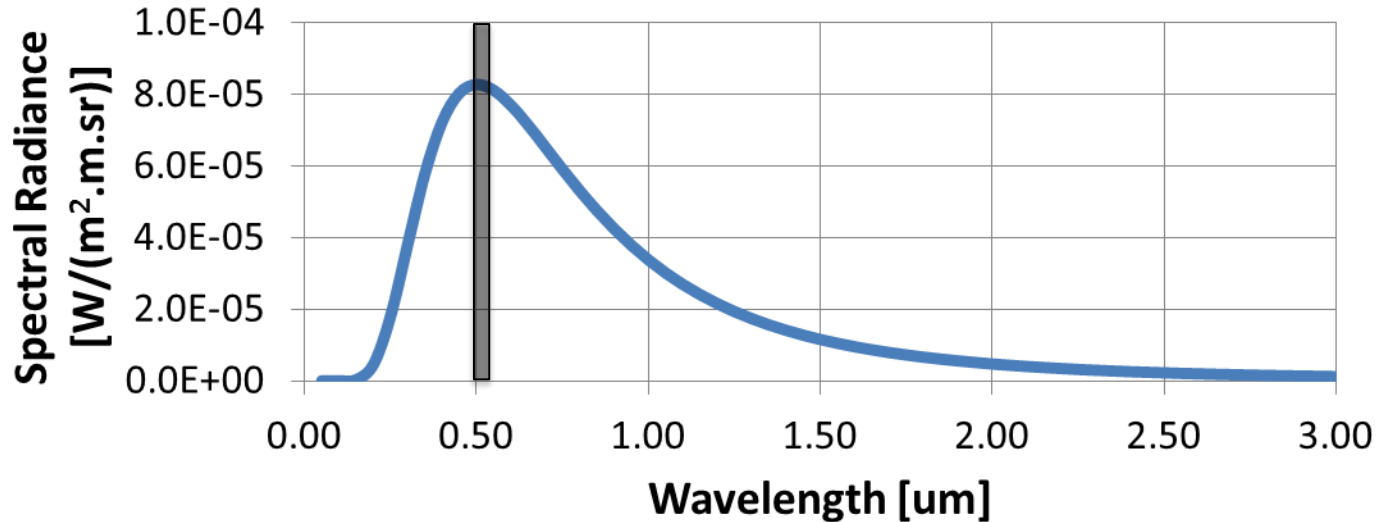
## *Imaging*



□ Mode:	100m-6km	30m-300m
□ Max ToF:	40 $\mu$ s	2 $\mu$ s
□ Precision:	1m (6.6ns)	10cm (660ps)

**Wide DR and long light time-of-flight**

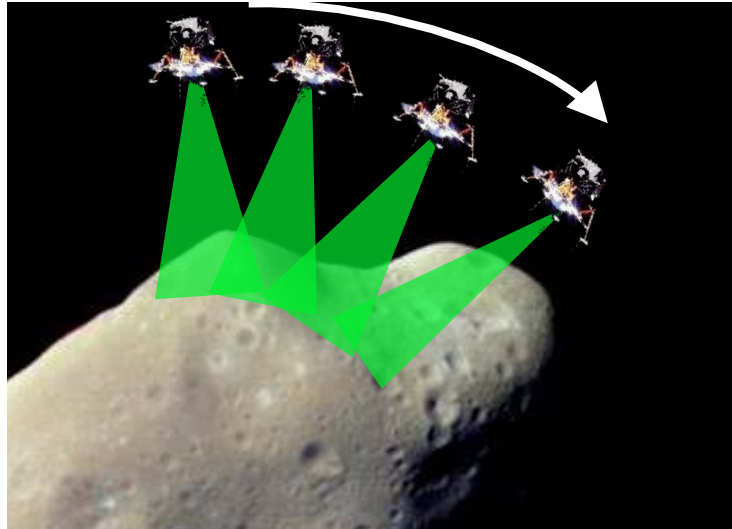
# Immunity to background light



- With targeted pixel size and FF:
    - 100 Mph/s (detected)
- } *5nm filter*  
} *Albedo <0.4*  
} *Sun angle 30°*

**High Background Rejection**

# Acquisition speed



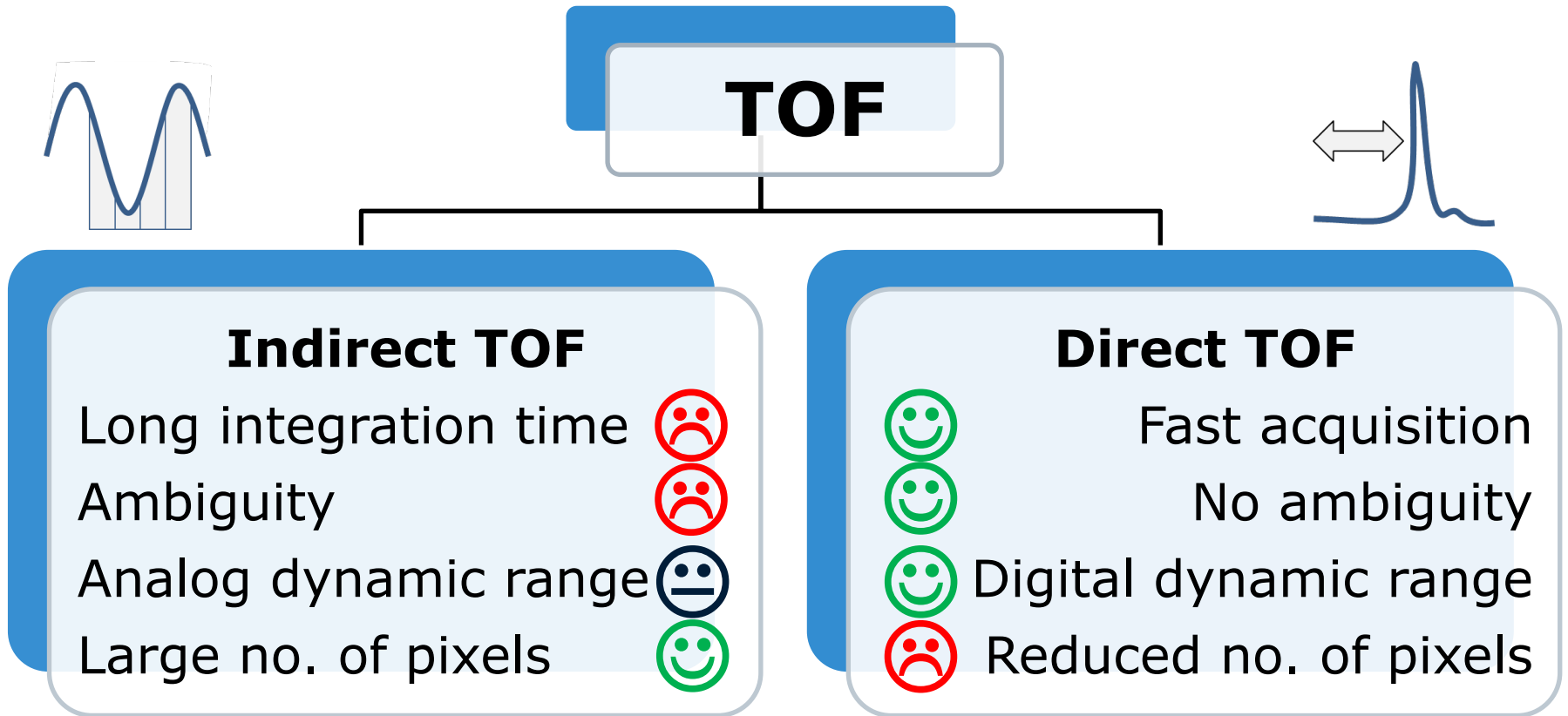
Spacecraft speed:  
0.1 m/s - 1.5 m/s

- No artifacts within 1 pixel
- Fast image acquisition  $< 2$  ms
- Low frame rate  $\approx 2$  fps

} *Enabling  
post-processing*

**Short Acquisition Time**

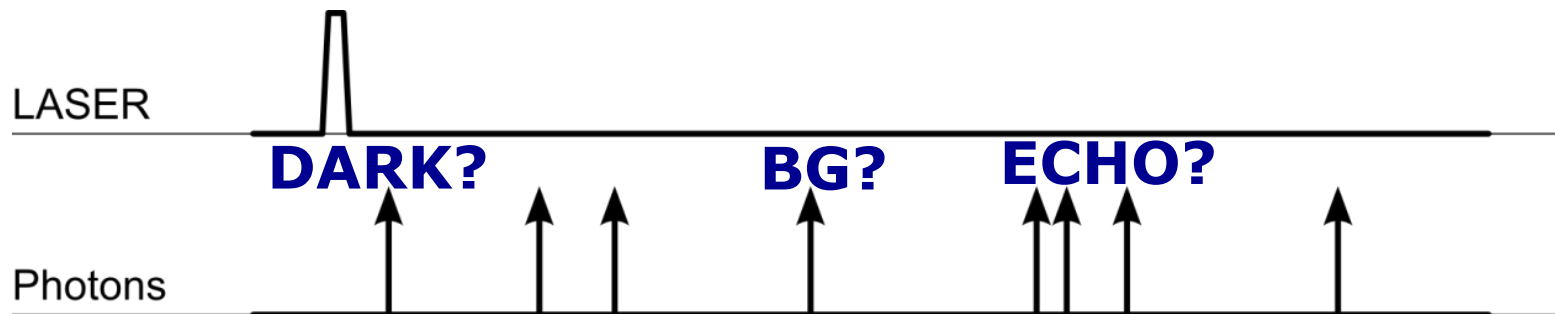
# TOF Ranging Techniques



**Challenge: single-photon detectors are BG sensitive and noisy**

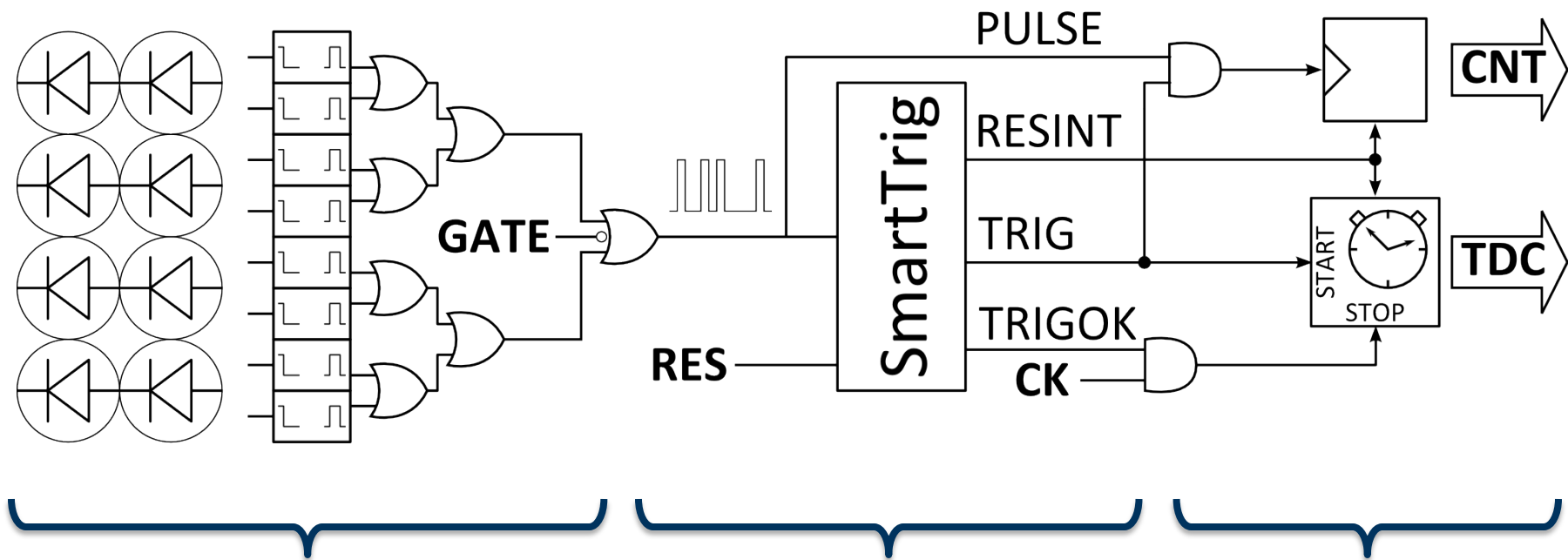
# Previous Solutions Limitations

- **Single SPAD + TDC** [Veerappan, ISSCC 2011]
  - Compact pixel (but low FF) 😊
  - First event (dark, bg, echo...): TDC timestamp 😞



- **Multiple SPAD + TDC** [Niclass, JSSC 2014]
  - First relevant event captured 😊
  - Few pixels, imaging through scanning 😞

# Pixel Schematic



**Digital SiPM**

**Triggering Logic**

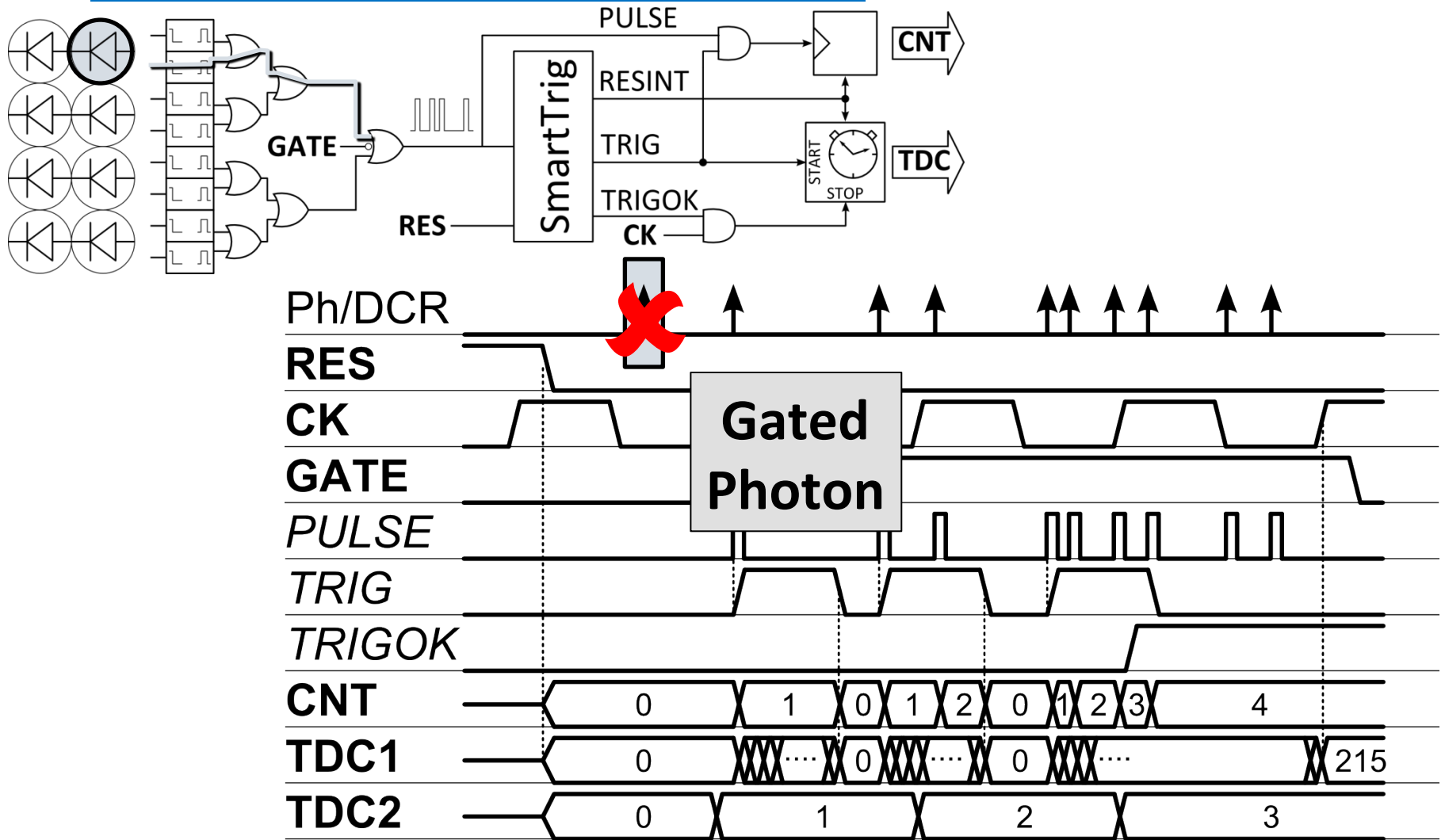
**Counter & TDC**

Smaller deadtime

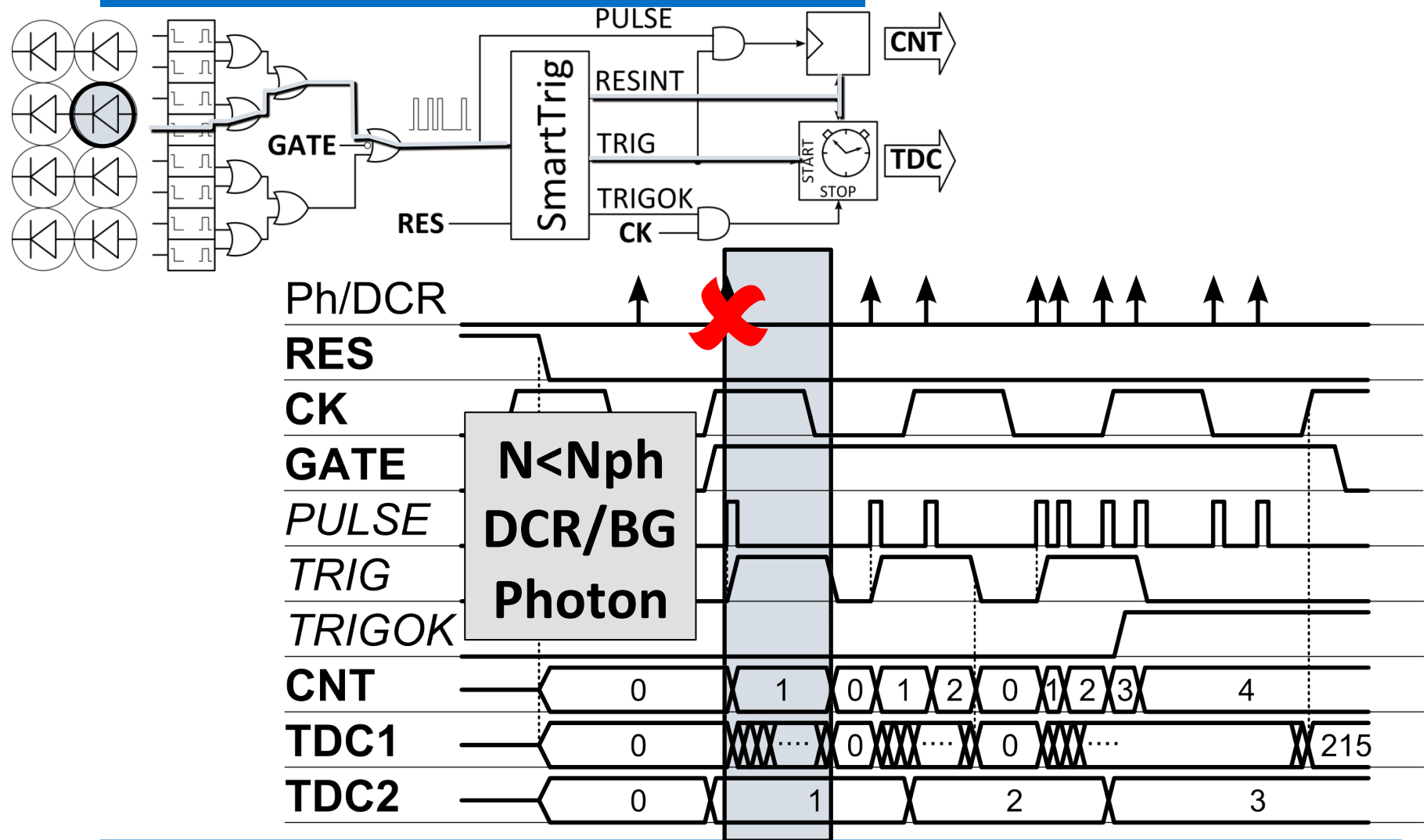
Identify echo

Timestamp  
and count

# Detailed Operation (1)

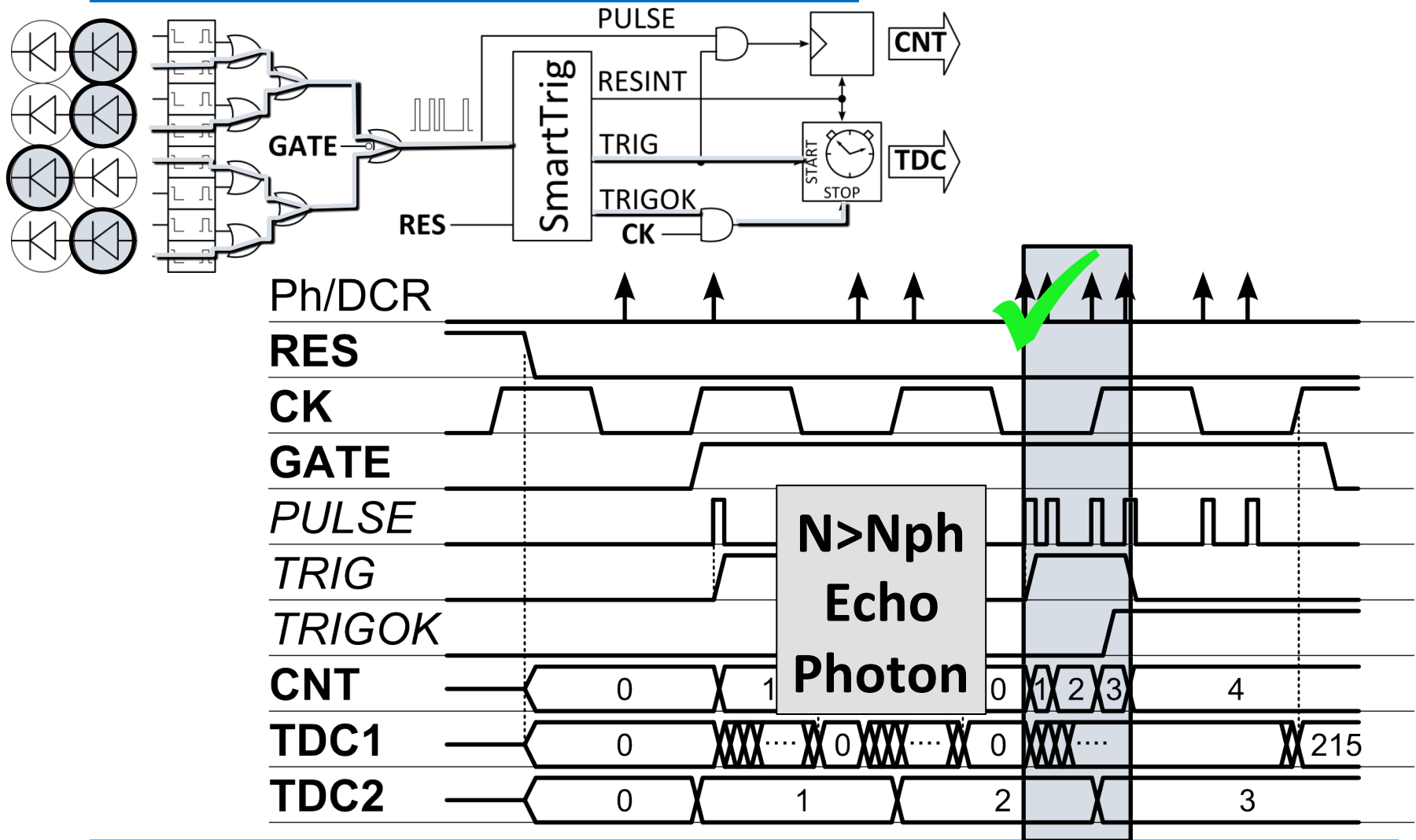


# Detailed Operation (2)

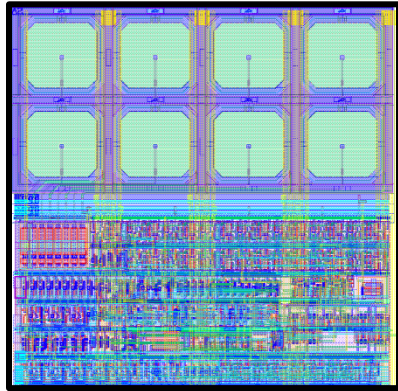




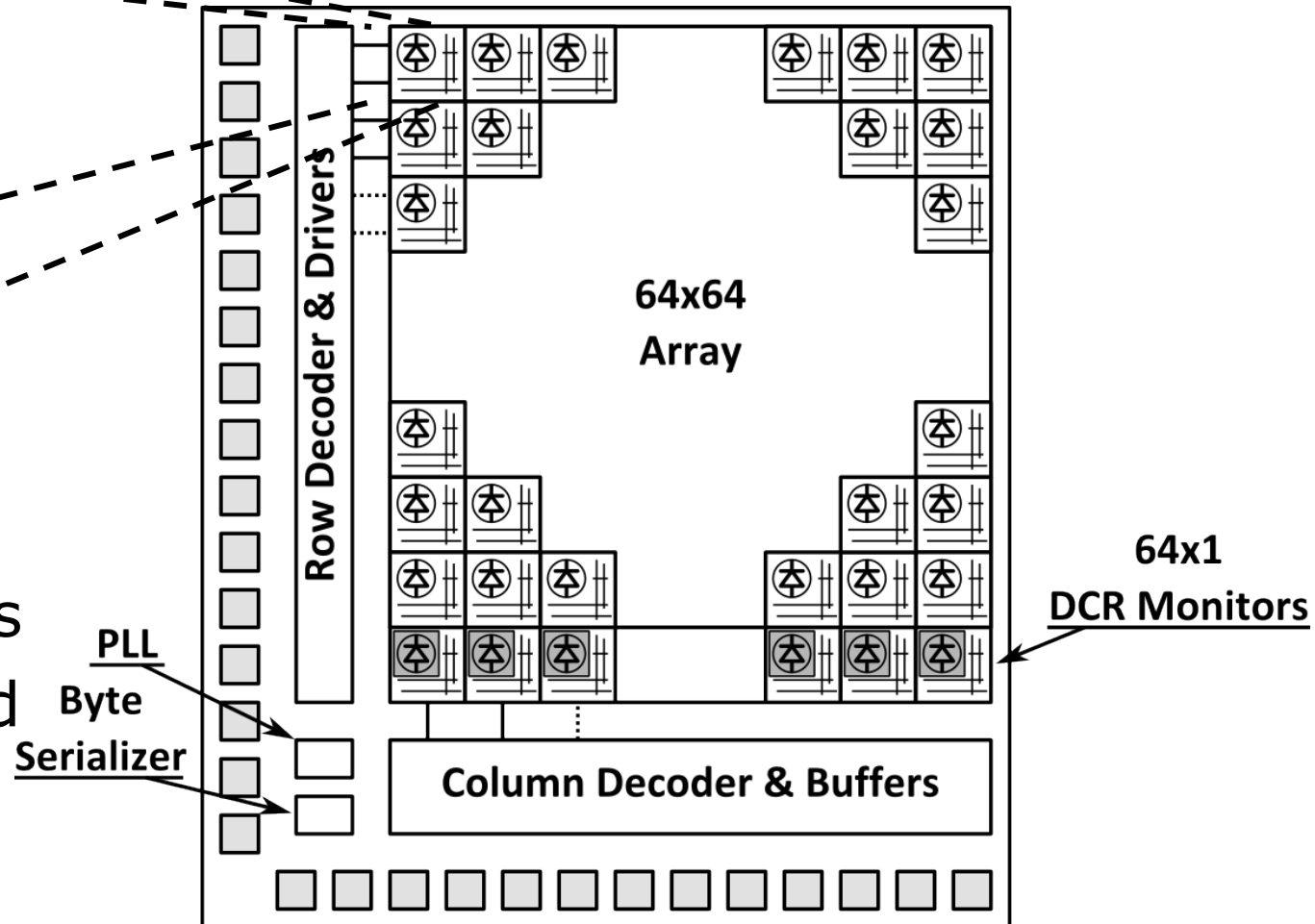
# Detailed Operation (3)



# Chip Architecture

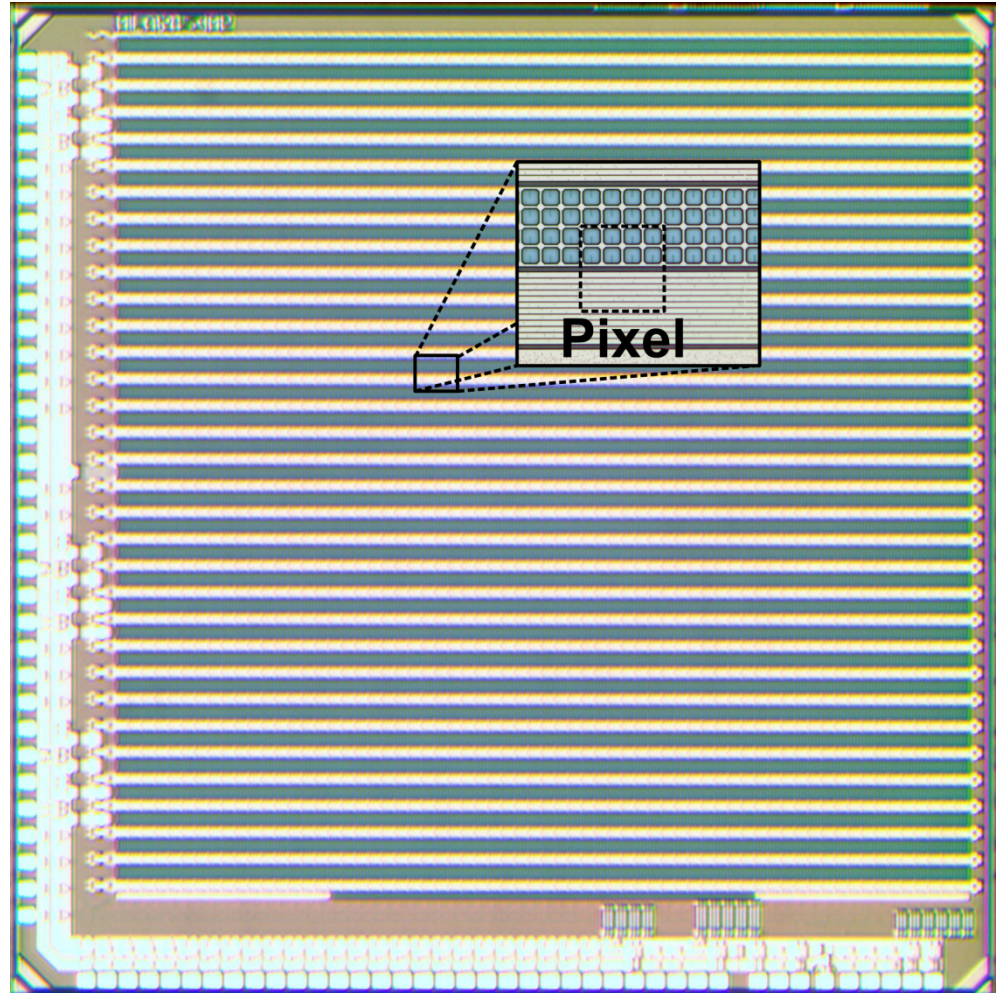


- 60- $\mu\text{m}$  pitch
- 26.5% FF
- 16-bit TDC
  - LSB 250ps
  - PLL-locked
- 4-bit CNT

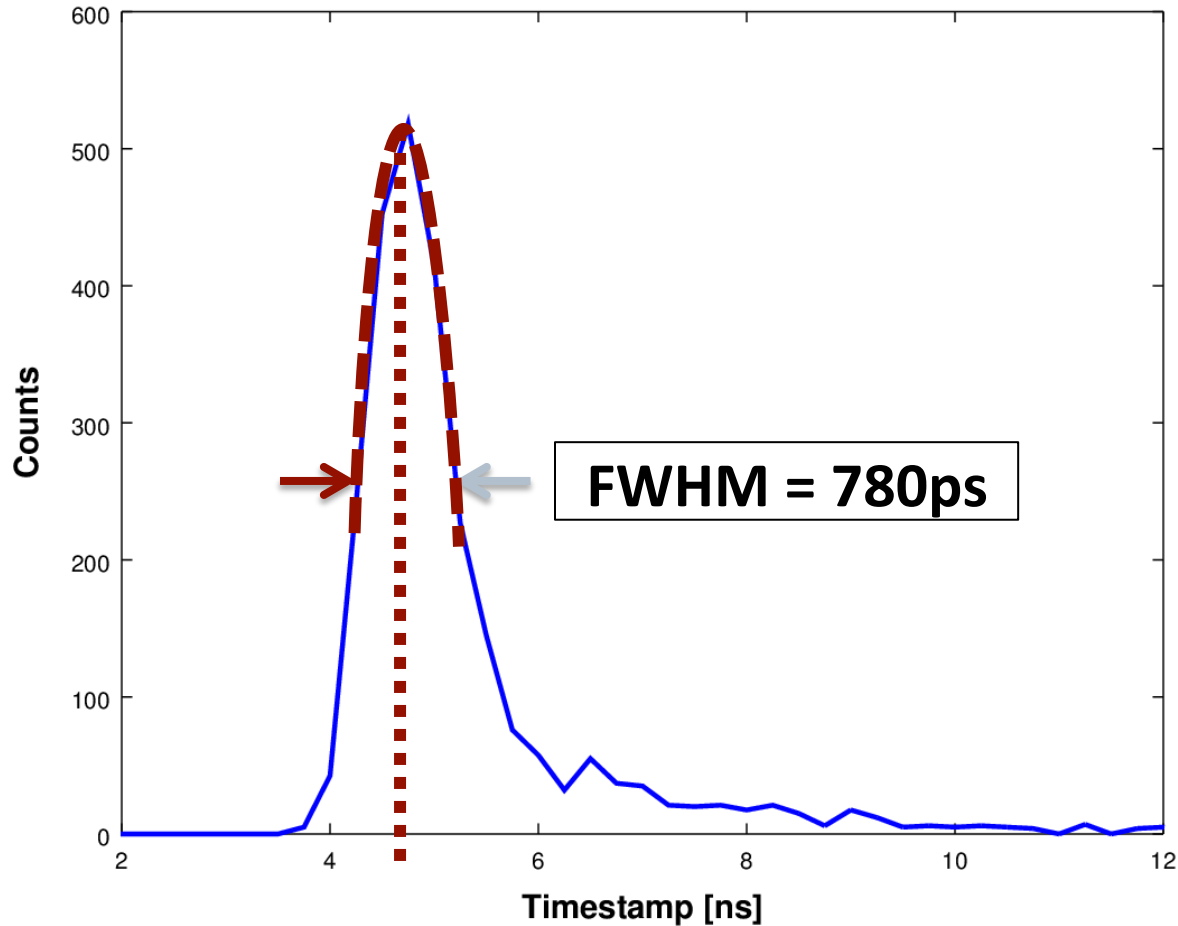


# Chip Micrograph

- 150nm CMOS
- $4.4 \times 4.4 \text{mm}^2$
- $P_{el} = 47.7 \text{mW}$
- $P_{SPAD} = 45.8 \text{mW}$
- 1920 fps

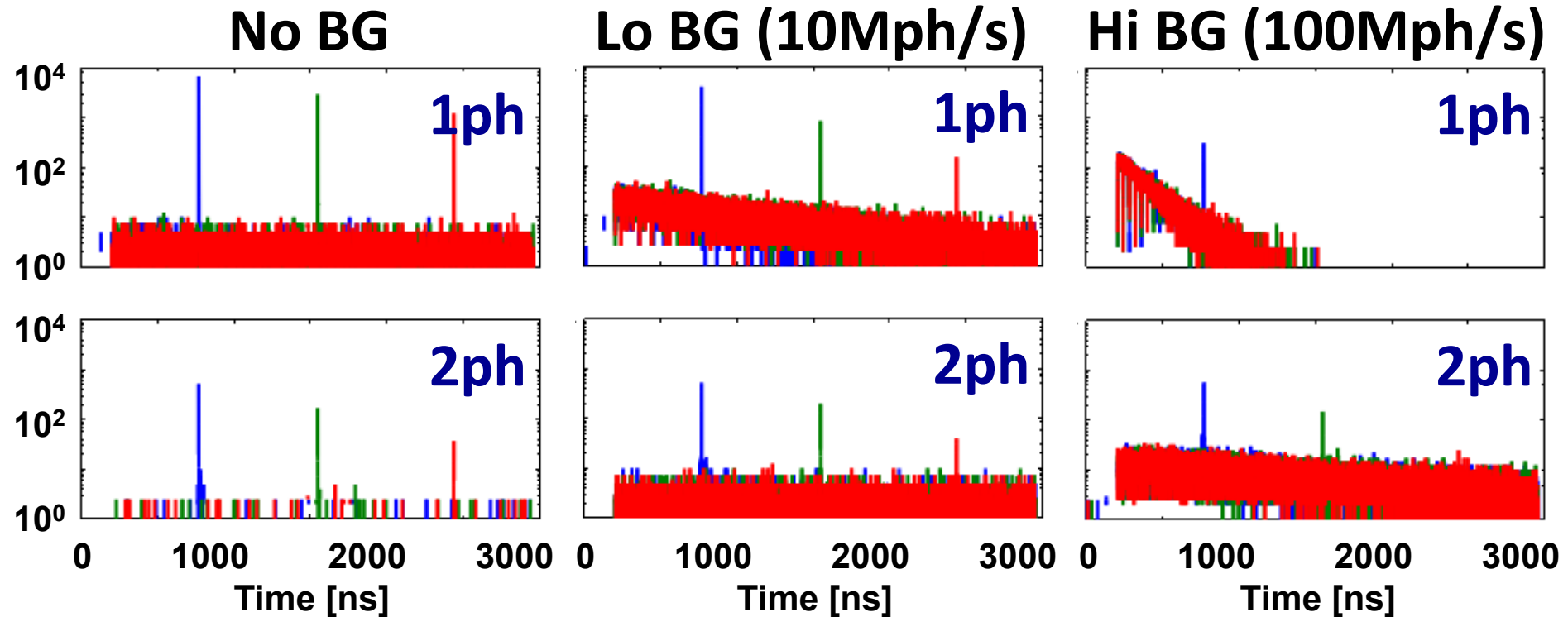


# Timing Resolution



- Conditions:
- 70-ps Laser (attenuated)
- 5000 frames
- Single pixel
- 250-ps LSB

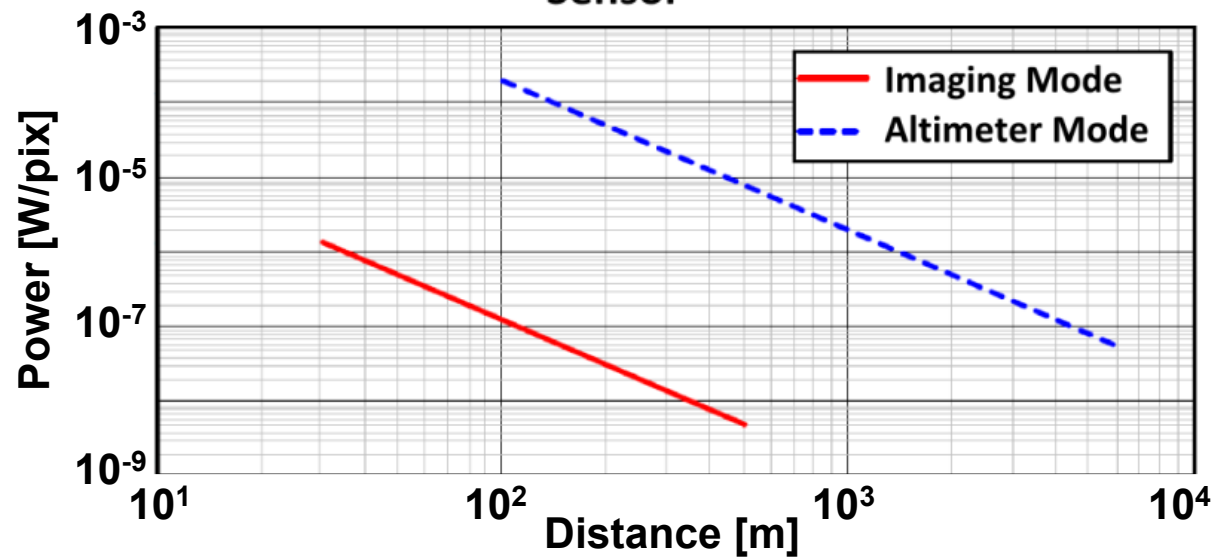
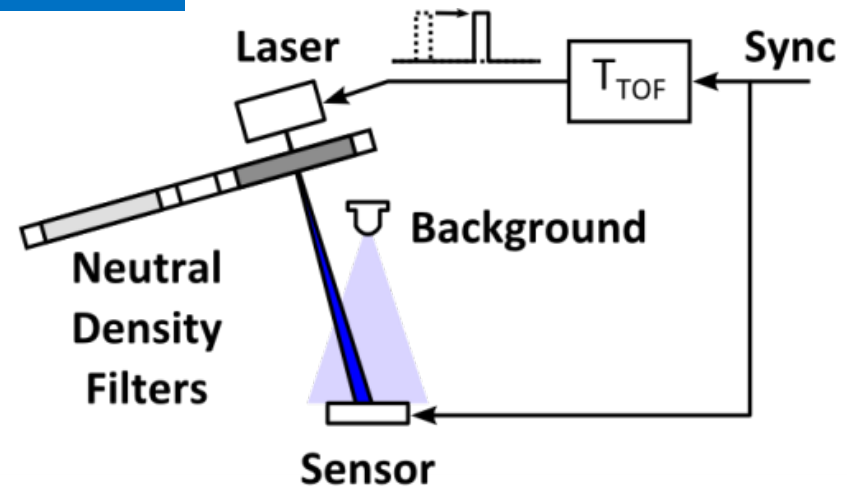
# Pile-up With Smart Trigger



- Strong background/DCR is rejected
- Smaller laser peaks

# Real Conditions Emulation

- Test vehicle conditions:
  - Laser:
    - $P_{pk} = 7.5\text{kW}$
    - 50% albedo
    - 2x2 sensors
    - $F\# = 0.8$
- 250-pts acq



# 3D Imaging Example

---

- <add here CSEM results>

*Courtesy of CSEM team (V. Mitev, J. Haesler, C. Pache, T. Herr, A. Pollini)*

# Conclusions

---

- FBK is developing CMOS SPAD for different applications
- This talk focuses on TOF sensor:
  - Imager with d-SiPM based pixel
  - Per-pixel multiple photon time correlation
  - Improved dark/BG counts rejection
- Future developments
  - Irradiation tests
  - Larger sensor